

## 0.5A, 50V - 1000V Fast Recovery Surface Mount Rectifier

### FEATURES

- Glass passivated chip junction
- Ideal for automated placement
- High temperature metallurgically bonded construction
- Fast switching for high efficiency
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

### APPLICATIONS

- DC to DC converter
- Switching mode converters and inverters
- General purpose

### MECHANICAL DATA

- Case: Sub SMA
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.019g (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
$I_F$	0.5	A
$V_{RRM}$	50 - 1000	V
$I_{FSM}$	10	A
$T_{JMAX}$	150	°C
Package	Sub SMA	
Configuration	Single die	



Sub SMA



ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)									
PARAMETER	SYMBOL	RSF AL	RSF BL	RSF DL	RSF GL	RSF JL	RSF KL	RSF ML	UNIT
Marking code on the device		FAL	FBL	FDL	FGL	FJL	FKL	FML	
Repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Reverse voltage, total rms value	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Forward current	$I_F$	0.5							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	10							A
Junction temperature	$T_J$	- 55 to +150							°C
Storage temperature	$T_{STG}$	- 55 to +150							°C

**THERMAL PERFORMANCE**

PARAMETER	SYMBOL	TYP	UNIT
Junction-to-case thermal resistance	$R_{\theta JC}$	32	°C/W
Junction-to-ambient thermal resistance	$R_{\theta JA}$	150	°C/W

**ELECTRICAL SPECIFICATIONS** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage <sup>(1)</sup>	$I_F = 0.5\text{A}, T_J = 25^\circ\text{C}$	$V_F$	-	1.3	V
Reverse current @ rated $V_R$ <sup>(2)</sup>	$T_J = 25^\circ\text{C}$	$I_R$	-	5	$\mu\text{A}$
	$T_J = 125^\circ\text{C}$		-	50	$\mu\text{A}$
Junction capacitance	1MHz, $V_R = 4.0\text{V}$	$C_J$	4	-	pF
Reverse recovery time	$I_F = 0.5\text{A}, I_R = 1.0\text{A}, I_{rr} = 0.25\text{A}$	$t_{rr}$	-	150	ns
			-	250	ns
			-	500	ns

**Notes:**

1. Pulse test with  $PW = 0.3\text{ms}$
2. Pulse test with  $PW = 30\text{ms}$

**ORDERING INFORMATION**

ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING
RSFxL	Sub SMA	10,000 / Tape & Reel

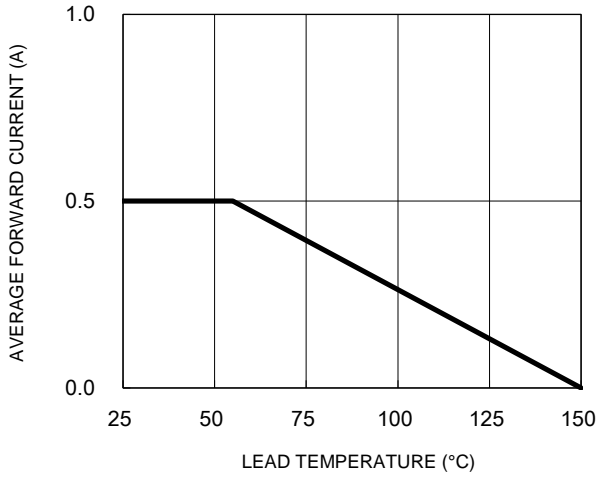
**Notes:**

1. "x" defines voltage from 50V(RSFAL) to 1000V(RSFML)

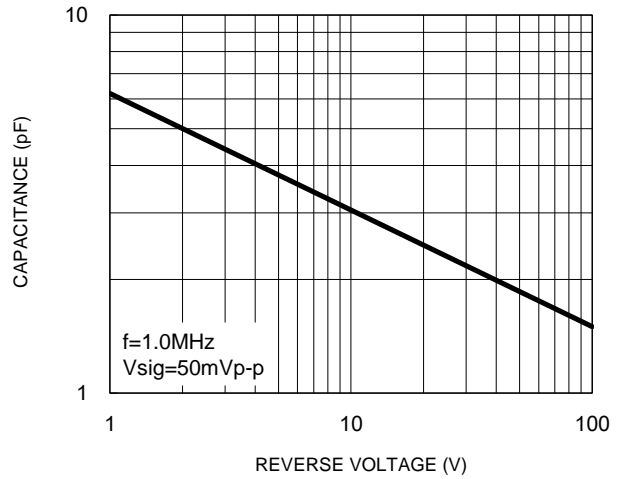
**CHARACTERISTICS CURVES**

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

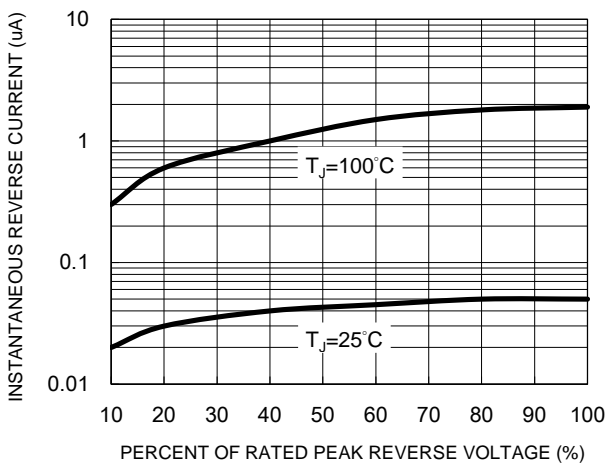
**Fig.1 Forward Current Derating Curve**



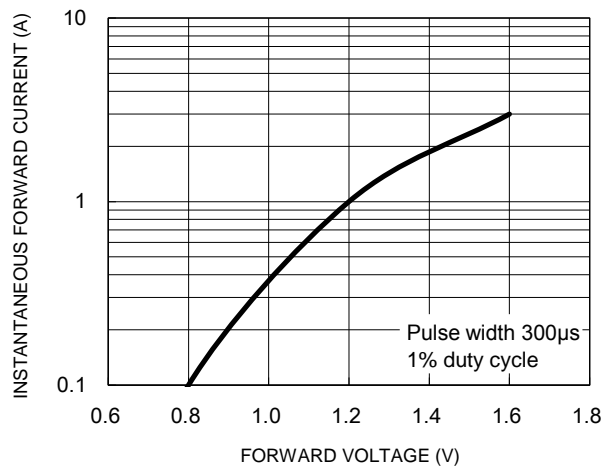
**Fig.2 Typical Junction Capacitance**



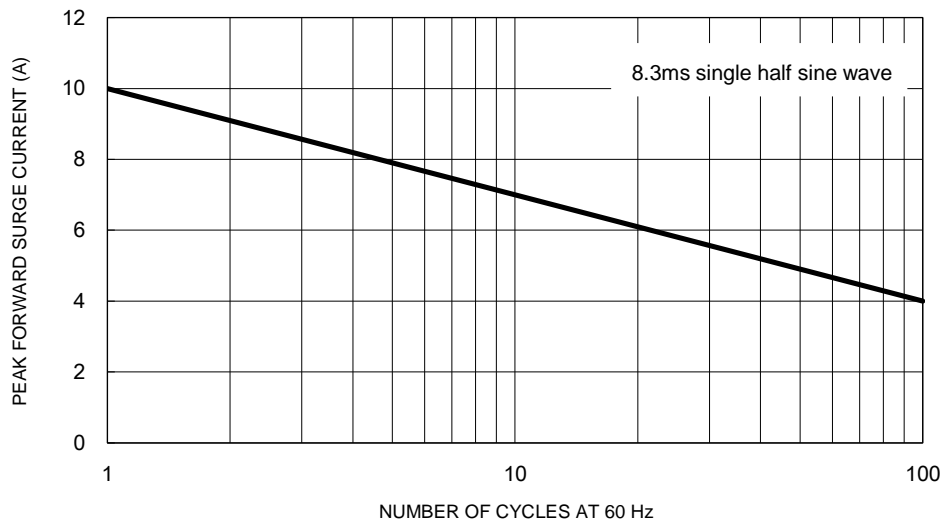
**Fig.3 Typical Reverse Characteristics**



**Fig.4 Typical Forward Characteristics**



**Fig.5 Maximum Non-Repetitive Forward Surge Current**



**CHARACTERISTICS CURVES**

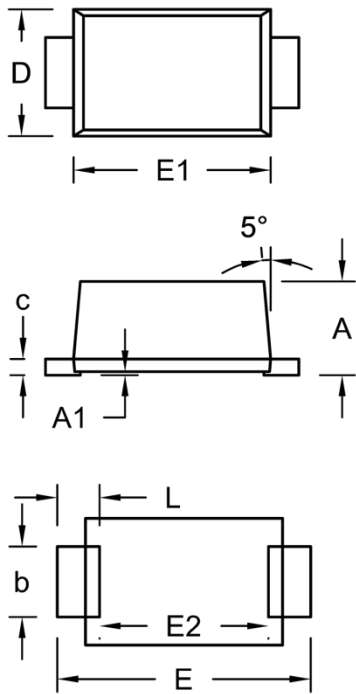
( $T_A = 25^\circ\text{C}$  unless otherwise noted)

**Fig.6 Reverse Recovery Time Characteristic and Test Circuit Diagram**



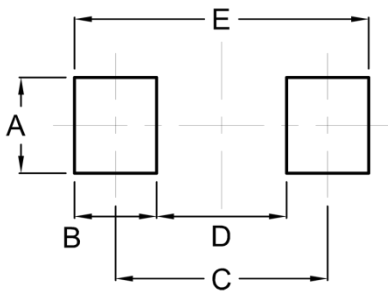
**PACKAGE OUTLINE DIMENSIONS**

Sub SMA



DIM.	Unit (mm)		Unit (inch)	
	Min.	Max.	Min.	Max.
A	1.23	1.43	0.048	0.056
A1	0.00	0.10	0.000	0.004
b	0.80	1.20	0.031	0.047
c	0.16	0.30	0.006	0.012
D	1.70	1.90	0.067	0.075
E	3.40	3.80	0.134	0.150
E1	2.70	2.90	0.106	0.114
E2	2.45	2.60	0.096	0.102
L	0.35	0.85	0.014	0.033

**SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
A	1.40	0.055
B	1.20	0.047
C	3.10	0.122
D	1.90	0.075
E	4.30	0.169

**MARKING DIAGRAM**



- P/N = Marking Code
- G = Green Compound
- YW = Date Code
- F = Factory Code